



Product Information Sheet

EPO-TEK® OD1001

Date: September 2017
Rev: VII
No. of Components: Single
Mix Ratio by Weight: N/A
Specific Gravity: 1.13
Pot Life: 28 Days
Shelf Life- Bulk: One year at -40°C

Recommended Cure: 125°C / 1 Hour

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

Product Description: A single component, thermally and electrically insulating epoxy designed for low stress semiconductor and electronics packaging. Low Tg, several weeks of pot life and low modulus are a few of its traits. It is particularly suitable for bonding, sealing and potting ferrite cores in power device plastic packaging. Adhesion to PCBs, ceramics, most metals and lead-frames is very good.

Typical Properties: Cure condition: 125°C / 1 Hour Different batches, conditions & applications yield differing results.
Data below is not guaranteed. To be used as a guide only, not as a specification. * denotes test on lot acceptance basis

PHYSICAL PROPERTIES:

* Color (before cure):	Cream
* Consistency:	Smooth thin paste
* Viscosity (23°C) @ 100 rpm:	1,000 - 1,500 cPs
Thixotropic Index:	1.2
* Glass Transition Temp:	≥ 35 °C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)
Coefficient of Thermal Expansion (CTE):	
Below Tg:	66 x 10 ⁻⁶ in/in°C
Above Tg:	211 x 10 ⁻⁶ in/in°C
Shore D Hardness:	70
Lap Shear @ 23°C:	> 1,800 psi
Die Shear @ 23°C:	≥ 15 Kg 5,334 psi
Degradation Temp:	355 °C
Weight Loss:	
@ 200°C:	0.27 %
@ 250°C:	0.64 %
@ 300°C:	1.50 %
Suggested Operating Temperature:	< 275 °C (Intermittent)
Storage Modulus:	168,765 psi
* Particle Size:	≤ 10 microns

ELECTRICAL AND THERMAL PROPERTIES:

Thermal Conductivity:	N/A
Volume Resistivity @ 23°C:	≥ 2 x 10 ¹³ Ohm-cm
Dielectric Constant (1KHz):	3.05
Dissipation Factor (1KHz):	0.011

OPTICAL PROPERTIES @ 23°C:

Spectral Transmission:	< 50% @ 300 - 1,200 nm
Refractive Index:	1.5413 @589 nm

This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.

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